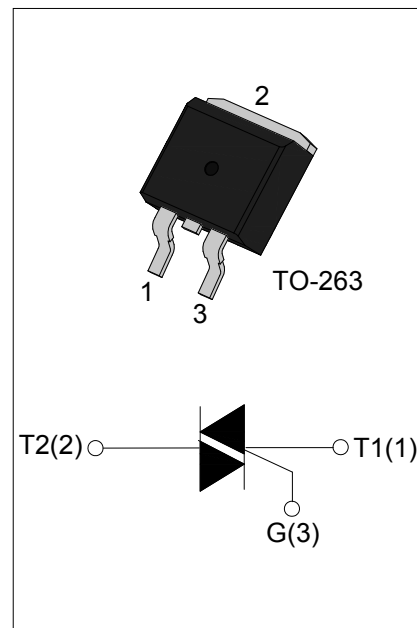




DESCRIPTION:

With high ability to withstand the shock loading of large current, JST16 series triacs provide high dv/dt rate with strong resistance to electromagnetic interface. With high commutation performances, 3 quadrants products especially recommended for use on inductive load. Package TO-263 is RoHS compliant. (2011/65/EU)



MAIN FEATURES

Symbol	Value	Unit
$I_{T(RMS)}$	16	A
V_{DRM} / V_{RRM}	600/800/1200	V

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit	
Storage junction temperature range	T_{stg}	-40-150	°C	
Operating junction temperature range	T_j	-40-125	°C	
Repetitive peak off-state voltage ($T_j=25^\circ\text{C}$)	V_{DRM}	600/800/1200	V	
Repetitive peak reverse voltage ($T_j=25^\circ\text{C}$)	V_{RRM}	600/800/1200	V	
Non repetitive surge peak Off-state voltage	V_{DSM}	$V_{DRM} + 100$	V	
Non repetitive peak reverse voltage	V_{RSM}	$V_{RRM} + 100$	V	
RMS on-state current	$I_{T(RMS)}$	TO-263 ($T_C=80^\circ\text{C}$)	16	A
Non repetitive surge peak on-state current (full cycle, F=50Hz)		I_{TSM}	160	A
I^2t value for fusing ($t_p=10\text{ms}$)	I^2t	128	A^2s	
Critical rate of rise of on-state current ($I_G=2 \times I_{GT}$)	di/dt	50	$\text{A}/\mu\text{s}$	
Peak gate current	I_{GM}	4	A	
Average gate power dissipation	$P_{G(AV)}$	1	W	
Peak gate power	P_{GM}	5	W	

ELECTRICAL CHARACTERISTICS ($T_j=25^{\circ}\text{C}$ unless otherwise specified)

3 Quadrants

Symbol	Test Condition	Quadrant		Value				Unit
				BW	CW	SW	TW	
I_{GT}	$V_D=12\text{V } R_L=33\Omega$	I - II -III	MAX	50	35	10	5	mA
V_{GT}		I - II -III	MAX	1.3				V
V_{GD}	$V_D=V_{DRM} T_j=125^{\circ}\text{C}$ $R_L=3.3\text{K}\Omega$	I - II -III	MIN	0.2				V
I_L	$I_G=1.2I_{GT}$	I -III	MAX	70	50	30	15	mA
		II		80	60	40	20	
I_H	$I_T=100\text{mA}$		MAX	60	40	25	15	mA
dV/dt	$V_D=2/3V_{DRM}$ Gate Open $T_j=125^{\circ}\text{C}$		MIN	1000	500	200	100	V/ μs

4 Quadrants

Symbol	Test Condition	Quadrant		Value		Unit
				B	C	
I_{GT}	$V_D=12\text{V } R_L=33\Omega$	I - II -III	MAX	50	25	mA
		IV		70	50	
V_{GT}		ALL	MAX	1.5		V
V_{GD}	$V_D=V_{DRM} T_j=125^{\circ}\text{C}$ $R_L=3.3\text{K}\Omega$	ALL	MIN	0.2		V
I_L	$I_G=1.2I_{GT}$	I -III-IV	MAX	70	50	mA
		II		100	80	
I_H	$I_T=100\text{mA}$		MAX	60	40	mA
dV/dt	$V_D=2/3V_{DRM}$ Gate Open $T_j=125^{\circ}\text{C}$		MIN	500	200	V/ μs

STATIC CHARACTERISTICS

Symbol	Parameter		Value(MAX)			Unit
			-600V	-800V	-1200V	
V_{TM}	$I_{TM}=22.5\text{A } t_p=380\mu\text{s}$	$T_j=25^{\circ}\text{C}$	1.5			V
I_{DRM}	$V_D=V_{DRM} V_R=V_{RRM}$	$T_j=25^{\circ}\text{C}$	5	5	10	μA
I_{RRM}		$T_j=125^{\circ}\text{C}$	1	1	2	mA

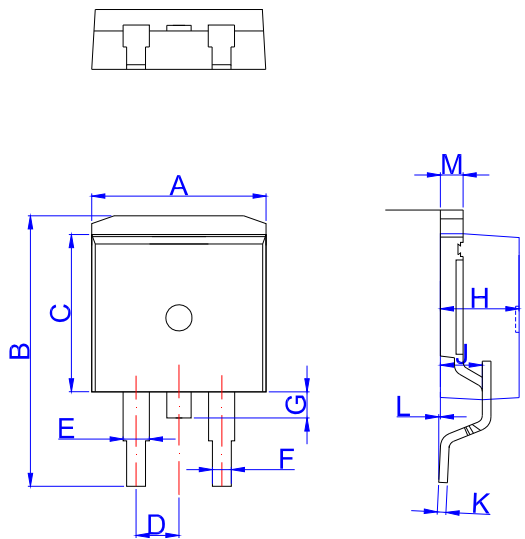
THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	junction to case(AC)	TO-263	2.5	°C/W
$R_{th(j-a)}$	junction to ambient		45	

ORDERING INFORMATION

JieJie Microelectronics Co.,Ltd Triacs $I_{T(RMS)}: 16A$ E: TO-263 ETR: TO-263(Tape&Reel)	J	ST	16	E	-600	BW	BW: $I_{GT1-3} \leq 50mA$ CW: $I_{GT1-3} \leq 35mA$ SW: $I_{GT1-3} \leq 10mA$ TW: $I_{GT1-3} \leq 5mA$ B: $I_{GT1-3} \leq 50mA$ $I_{GT4} \leq 70mA$ C: $I_{GT1-3} \leq 25mA$ $I_{GT4} \leq 50mA$
600: $V_{DRM} / V_{RRM} \geq 600V$ 800: $V_{DRM} / V_{RRM} \geq 800V$ 1200: $V_{DRM} / V_{RRM} \geq 1200V$							

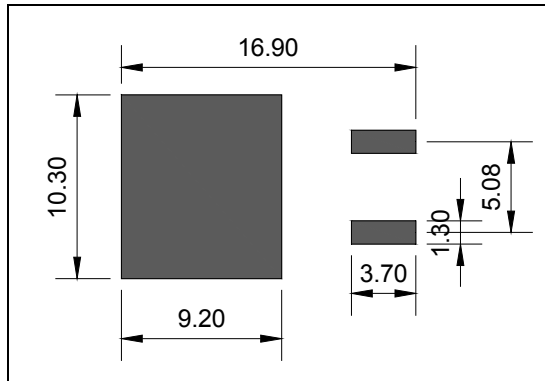
PACKAGE MECHANICAL DATA



TO-263

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	9.90		10.20	0.390		0.402
B	14.70		15.80	0.579		0.622
C	9.4		9.6	0.37		0.378
D		2.54			0.100	
E	1.20		1.40	0.047		0.055
F	0.75		0.85	0.029		0.033
G			1.75			0.069
H	4.40		4.70	0.173		0.185
J	2.30		2.70	0.091		0.106
K	0.38		0.55	0.015		0.022
L	0	0.10	0.25	0	0.004	0.010
M	1.25		1.35	0.049		0.053

FOOTPRINT-TO-263 (dimensions in mm)



PACKAGE INFORMATION

PACKAGE	OUTLINE	TUBE (PCS)	INNER BOX (PCS)	PER CARTON
TO-263	TUBE	50	1,000	6,000
PACKAGE	OUTLINE	REEL (PCS)	PER CARTON (PCS)	TAPE & REEL
TO-263	TAPING	800	4,000	13 inch

MARKING

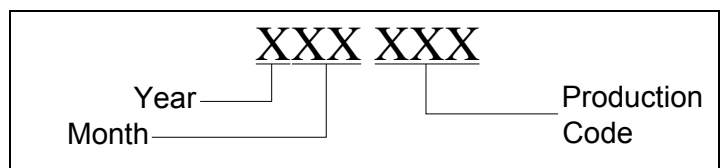
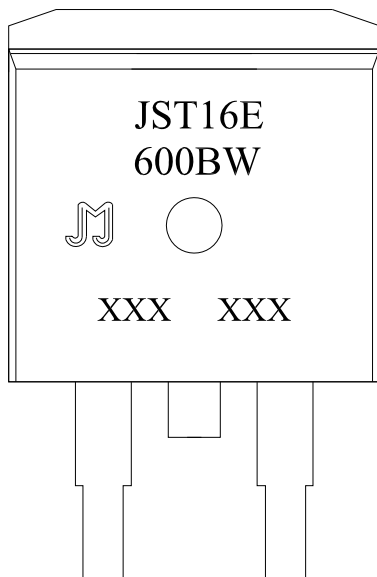


FIG.1 Maximum power dissipation versus RMS on-state current

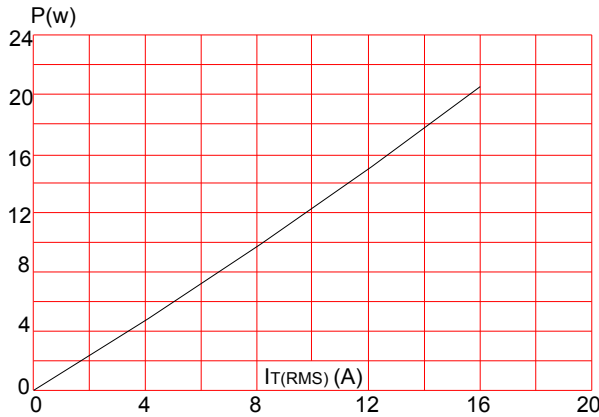


FIG.3: Surge peak on-state current versus number of cycles

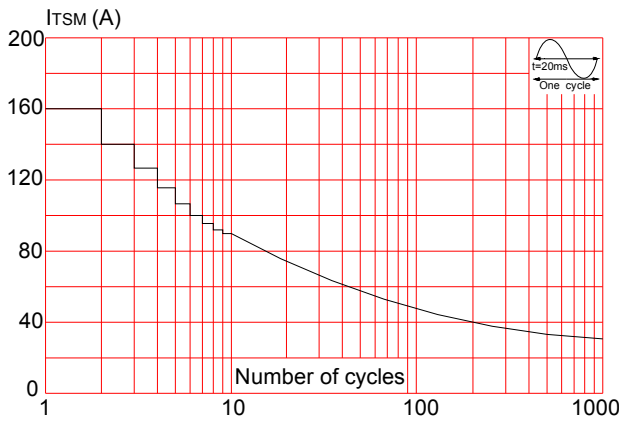


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 20\text{ms}$, and corresponding value of I^2t ($di/dt < 50\text{A}/\mu\text{s}$)

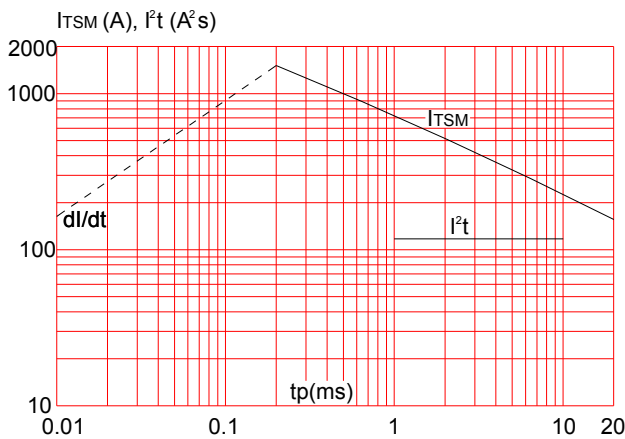


FIG.2: RMS on-state current versus ambient temperature (printed circuit board FR4, copper thickness: $35\mu\text{m}$) (full cycle)

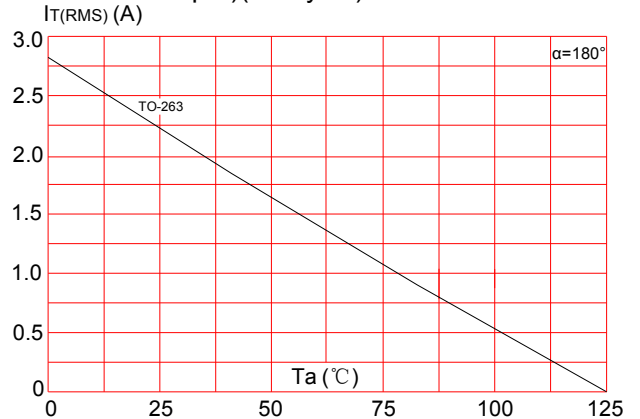


FIG.4: On-state characteristics (maximum values)

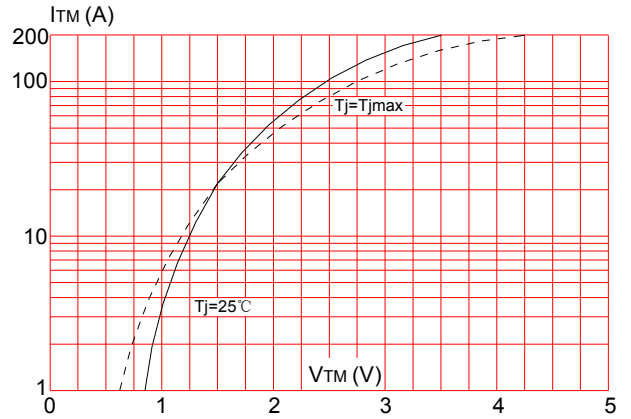
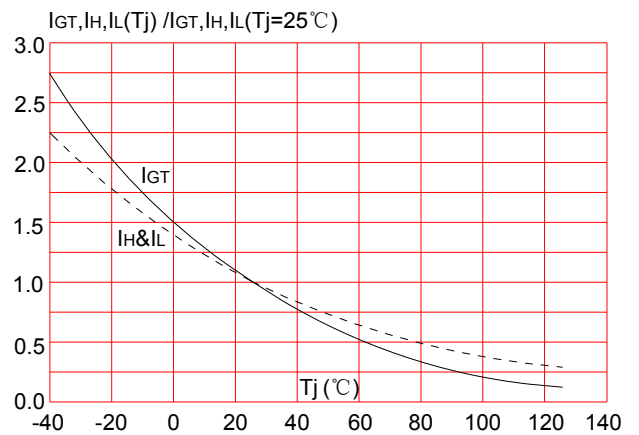
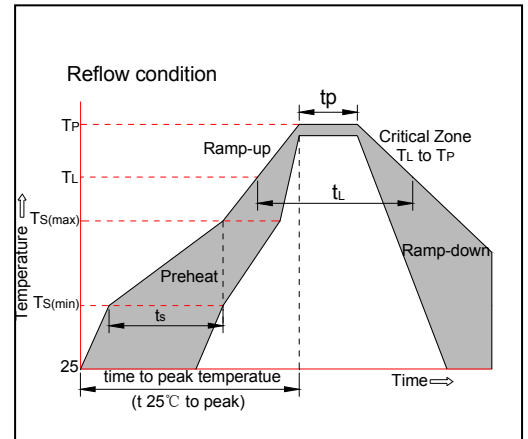


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature




SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L) (Liquidus)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



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